LY M67K

Mini TOPLED®









Applications

- Cluster, Button Backlighting
- Electronic Equipment

- Interior Illumination e.g. Ambient Map
- White Goods

Features:

- Package: white SMT package, colorless clear resin
- Chip technology: InGaAIP
- Typ. Radiation: 120° (Lambertian emitter)
- Color: $\lambda_{dom} = 587 \text{ nm}$ (• yellow)
- Corrosion Robustness Class: 3B
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)



Ordering Information				
Туре	Luminous Intensity 1) I _F = 2 mA I _V	Ordering Code		
LY M67K-J1L2-26	4.5 18.0 mcd	Q65110A2076		



LY M67K

Maximum Ratings			
Parameter	Symbol		Values
Operating Temperature	T _{op}	min. max.	-40 °C 100 °C
Storage Temperature	T_{stg}	min. max.	-40 °C 100 °C
Junction Temperature	T _j	max.	125 °C
Forward current T _S = 25 °C	I _F	max.	20 mA
Surge Current t \leq 10 µs; D = 0.005 ; T _s = 25 °C	I _{FS}	max.	100 mA
Reverse voltage ²⁾ T _S = 25 °C	V_R	max.	12 V
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	V_{ESD}		2 kV



Characteristics

 $I_F = 2 \text{ mA}; T_S = 25 \text{ }^{\circ}\text{C}$

Parameter	Symbol	Values	
Peak Wavelength	λ_{peak}	typ.	591 nm
Dominant Wavelength 3)	λ_{dom}	min.	580 nm
$I_F = 2 \text{ mA}$	dom	typ.	587 nm
		max.	595 nm
Spectral Bandwidth at 50% I _{rel,max}	Δλ	typ.	15 nm
Viewing angle at 50 % $\rm I_{\rm V}$	2φ	typ.	120 °
Forward Voltage 4)	V _F	min.	1.70 V
$I_F = 2 \text{ mA}$	·	typ.	1.80 V
		max.	2.20 V
Reverse current ²⁾	I _R	typ.	0.01 μΑ
V _R = 12 V		max.	10 µA
Temperature Coefficient of Peak Wavelength -10°C ≤ T ≤ 100°C	$TC_{\lambda peak}$	typ.	0.12 nm / K
Temperature Coefficient of Dominant Wavelength -10°C ≤ T ≤ 100°C	$TC_{\lambda dom}$	typ.	0.09 nm / K
Temperature Coefficient of Forward Voltage -10°C ≤ T ≤ 100°C	TC_{VF}	typ.	-2.1 mV / K
Real thermal resistance junction/ambient 5), 6)	R _{thJA real}	max.	530 K / W
Real thermal resistance junction/solderpoint 5)	R _{thJS real}	max.	280 K / W



Brightness Groups

Group	Luminous Intensity ¹⁾ I _F = 2 mA min. I _V	Luminous Intensity. 1) I _F = 2 mA max. I _v	Luminous Flux 7) $I_F = 2 \text{ mA}$ $typ.$ Φ_V		
J1	4.5 mcd	5.6 mcd	15.1 mlm		
J2	5.6 mcd	7.1 mcd	19.0 mlm		
K1	7.1 mcd	9.0 mcd	24.2 mlm		
K2	9.0 mcd	11.2 mcd	30.3 mlm		
L1	11.2 mcd	14.0 mcd	37.8 mlm		
L2	14.0 mcd	18.0 mcd	48.0 mlm		

Wavelength Groups

Group Dominant Wavelength $^{3)}$ $I_F = 2 \text{ mA}$		Dominant Wavelength ³⁾ I _F = 2 mA		
min.		max.		
	$\lambda_{\sf dom}$	$\lambda_{\sf dom}$		
2 580 nm		583 nm		
3	583 nm	586 nm		
4	586 nm	589 nm		
5	589 nm	592 nm		
6 592 nm		595 nm		

Group Name on Label

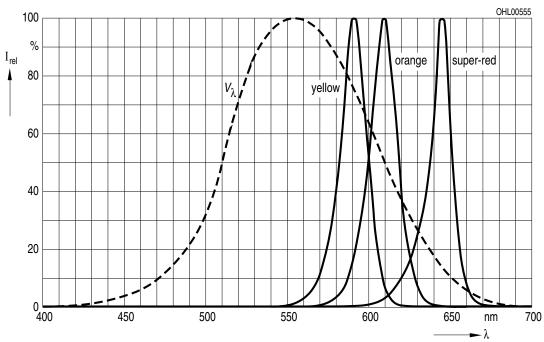
Brightness Wavelength

J1 2



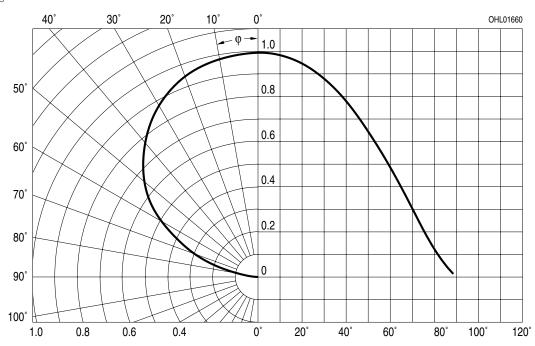
Relative Spectral Emission 7)

$$I_{rel} = f(\lambda); I_F = 2 \text{ mA}; T_S = 25 \text{ }^{\circ}\text{C}$$



Radiation Characteristics 7)

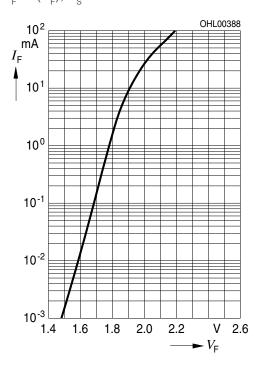
$$I_{rel} = f (\phi); T_S = 25 \, ^{\circ}C$$





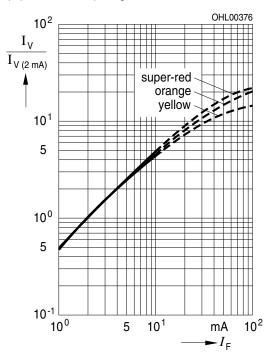
Forward current 7), 8)

$$I_F = f(V_F); T_S = 25 \, ^{\circ}C$$



Relative Luminous Intensity 7), 8)

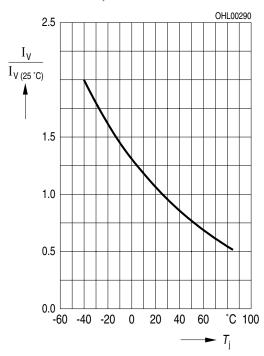
$$I_{v}/I_{v}(2 \text{ mA}) = f(I_{F}); T_{S} = 25 \text{ °C}$$





Relative Luminous Intensity 7)

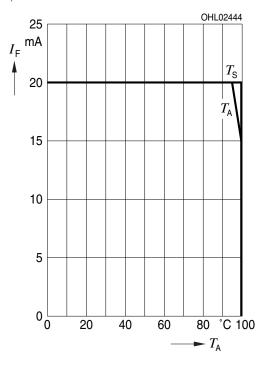
 $I_{v}/I_{v}(25 \text{ °C}) = f(T_{j}); I_{F} = 2 \text{ mA}$





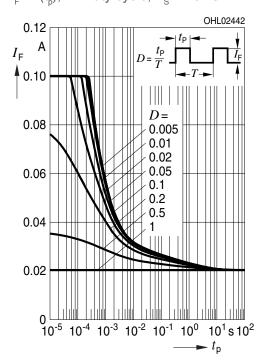
Max. Permissible Forward Current

 $I_{\scriptscriptstyle F} = f(T)$



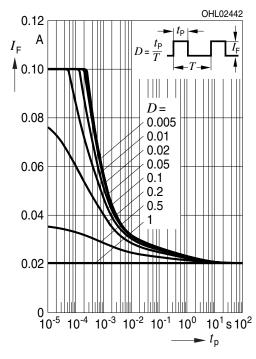
Permissible Pulse Handling Capability

 $I_{_{\rm F}}$ = f($t_{_{
m D}}$); D: Duty cycle; $T_{_{
m S}}$ = 25 °C

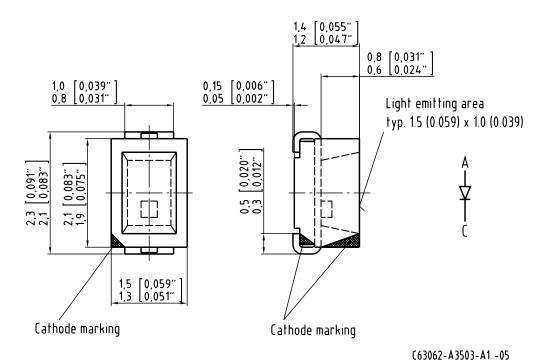


Permissible Pulse Handling Capability

 $I_{_{\rm F}}$ = f(t $_{_{
m D}}$); D: Duty cycle; $T_{_{
m S}}$ = 85 °C



Dimensional Drawing 9)



Approximate Weight: 7.0 mg

Package marking: Cathode

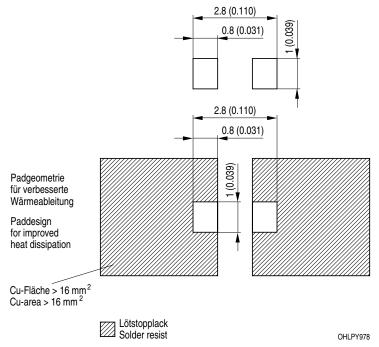
Corrosion test: Class: 3B

Test condition: 40° C / 90 % RH / 15 ppm H₂S / 14 days (stricter then IEC

60068-2-43)



Recommended Solder Pad 9)

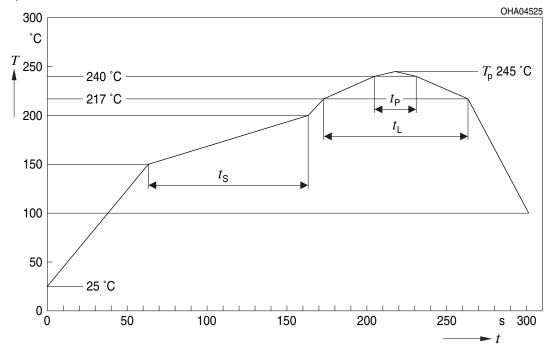


For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.



Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

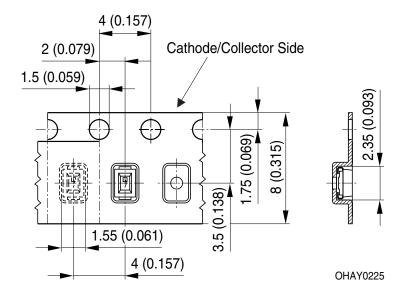


Profile Feature	Symbol	Pb	Pb-Free (SnAgCu) Assembly		
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t_s T_{Smin} to T_{Smax}	t _s	60	100	120	S
Ramp-up rate to peak*) T_{Smax} to T_{P}			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	$t_{\scriptscriptstyle \perp}$		80	100	S
Peak temperature	T _P		245	260	°C
Time within 5 °C of the specified peak temperature T _p - 5 K	t _P	10	20	30	S
Ramp-down rate* T _P to 100 °C			3	6	K/s
Time 25 °C to T _P				480	S

All temperatures refer to the center of the package, measured on the top of the component * slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

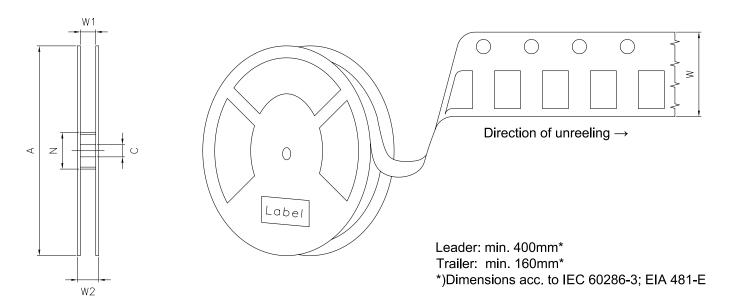


Taping 9)





Tape and Reel 10)



Reel dimensions [mm]

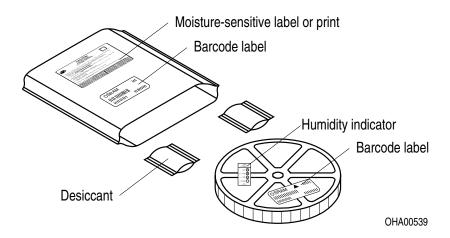
A	W	N_{min}	W ₁	$W_{2 max}$	Pieces per PU
180 mm	8 + 0.3 / - 0.1	60	8.4 + 2	14.4	3000



Barcode-Product-Label (BPL)



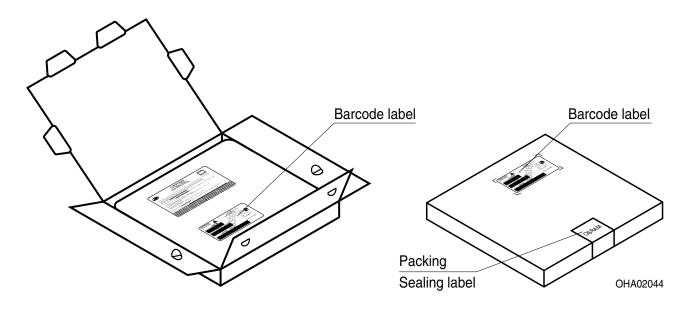
Dry Packing Process and Materials 9)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



Transportation Packing and Materials 9)



Dimensions of transportation box in mm

Width	Length	Height		
200 ± 5 mm	195 ± 5 mm	30 ± 5 mm		



Type Designation System

Wavel (λ _{dom} t	•	Emission Col			coordinates 31/Emissio		
	470 nm	blue			white		
	633 nm	super red			warm white		
T:	528 nm	true green			color on den		
Y: O:	587 nm 606 nm	yellow orange		CG: CL:	color on den		
G:	570 nm	green	`	, L .	color on ach	iana lagane	
P:	560 nm	pure green /			/ - .	_	
A:	617 nm	amber /		/	<pre>Package M: Mi</pre>	Type niTOPLED	
D:	460 nm	deep blue			IVI. 1VII	IIIIOFLLD	
L:	Light emitting diode						
L	A		I	M	6	7	6
4: 1 6: 1 T: 1	through hole folded leads folded leads, (Au-LF), w/o folded leads	improved corro TiO2 jetting and UX:3 w/ im _F), TiO2 jetting		·			
	- '	ant Type / Lens	Prope	erties			
		orless clear or w		olume	conversion		
		in encapsulation cone (with or wit		iffusei	-)		
	O. Oille	one (wan or wa	nout a	maoci	/ /		
		5: H 6: S B: H C: A F: T G: T S: s 1: ir	tandar IOP 20 tandar IOP 20 TON hinfilm hinGal Subcor IGaAlF	d InG 000 rd InG 000 n InGa N (Th n: Sap d InG	alP AIP infilm InGaN ophire) current aN low curre		/



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the LED specified in this data sheet fall into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. As is also true when viewing other bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this LED contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize LED exposure to aggressive substances during storage, production, and use. LEDs that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related informations please visit www.osram-os.com/appnotes



Disclaimer

Disclaimer

Language english will prevail in case of any discrepancies or deviations between the two language wordings.

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS webside.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office.

By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

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Glossary

- Brightness: Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ±8 % and an expanded uncertainty of ±11 % (acc. to GUM with a coverage factor of
- Reverse Operation: Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- 3) Wavelength: The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of ±0.5 nm and an expanded uncertainty of ±1 nm (acc. to GUM with a coverage factor of k =
- Forward Voltage: The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ±0.05 V and an expanded uncertainty of ±0.1 V (acc. to GUM with a coverage factor of k = 3).
- 5) **Thermal Resistance**: Rth max is based on statistic values (6σ).
- 6) Thermal Resistance: RthJA results from mounting on PC board FR 4 (pad size 16 mm² per pad)
- 7) Typical Values: Due to the special conditions of the manufacturing processes of LED, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 8) Characteristic curve: In the range where the line of the graph is broken, you must expect higher differences between single LEDs within one packing unit.
- 9) Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- Tape and Reel: All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



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